

<h1>Tentative</h1>		DA26101	
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DA26101

Silicon epitaxial planar type

For high speed switching circuits

Marking Symbol : A1

Package Code : ML2-N3-B

Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	80	V
Maximum peak reverse voltage	VRM	80	V
Forward current	IF	100	mA
Peak forward current	IFM	225	mA
Non-repetitive peak forward surge current *1	IFSM	500	mA
Junction temperature	Tj	125	$^\circ\text{C}$
Storage temperature	Tstg	-55 to +125	$^\circ\text{C}$

Pin name	1.	Cathode
	2.	Anode

Note: 1. *1 $t = 1\text{ s}$

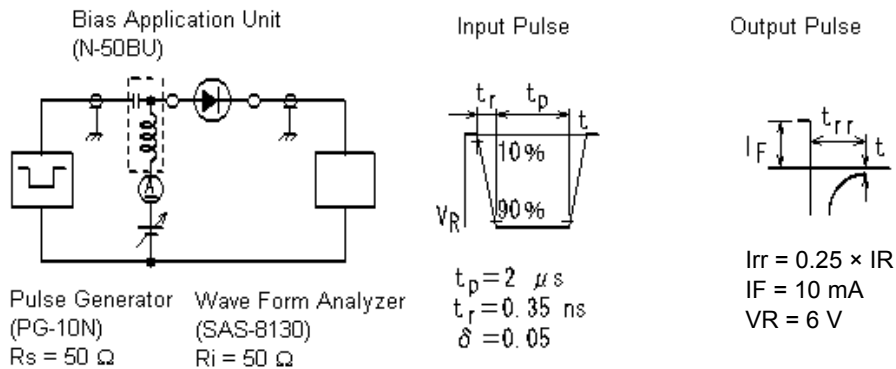
Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 100 mA		0.92	1.20	V
Reverse voltage	VR	IR = 100 μA	80			V
Reverse current	IR	VR = 80 V			100	nA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz			1.2	pF
Reverse recovery time *1	trr	IF = 10 mA, VR = 6 V Irr = 0.25 x IR			3	ns

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 100 MHz.

3. *1 trr test circuit



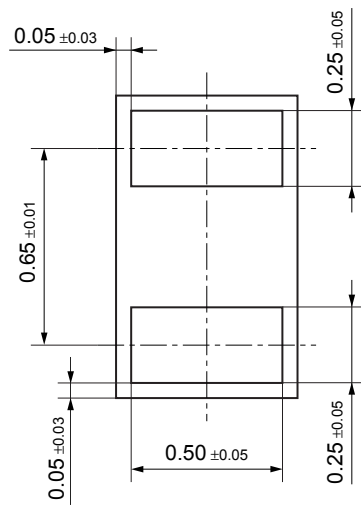
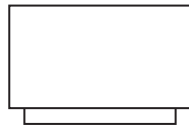
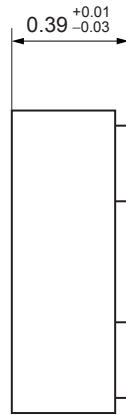
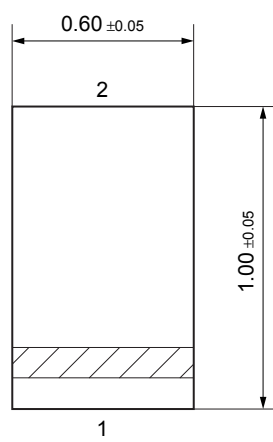
Packing

Embossed type (Thermo-compression sealing) : 10 000 pcs / reel

2010.4.7	2010.7.27	
Prepared	Revised	

ML2-N3-B

Unit: mm



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